# Conduction Shape Factor Models for 3-D Enclosures

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## Outline

- Introduction
- Literature review
- Model development
- Application and validation of models
- Summary and Conclusions



### Introduction

- Analytical models for conduction shape factors in enclosures
  - heated inner body
  - cooled surrounding enclosure
  - arbitrarily-shaped, concentric boundaries



- isothermal boundary conditions
- Limiting case for natural convection models for enclosures



#### Literature Review

- Numerical data
  - Hassani<sup>1</sup>

- concentric circular cylinders
- concentric, base-attached double cones
- Warrington et al.<sup>2</sup> concentric cubes
  - sphere in cubical enclosure
  - cube in spherical enclosure
- Analytical model Hassani and Hollands<sup>3</sup>

$$S = (S_0^m + S_\infty^m)^{1/m}, \quad S_0 = A_i / \delta, \quad S_\infty = 3.51 \sqrt{A_i}$$

- m = 1, concentric spheres linear superposition
- m > 1, other boundary shapes, dependent on geometry, inner area, aspect ratio
- limited to geometrically similar boundary shapes



# **Problem Definition**

• Conduction shape factor

$$S = \iint_{A_i} -\frac{\partial \psi}{\partial n} \bigg|_{A_i} dA_i$$
$$\psi = \frac{T(\vec{r}) - T_o}{T_i - T_o}$$

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- Dimensionless shape factor

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$$S_{\sqrt{A_i}}^* = \frac{S}{\sqrt{A_i}} = \frac{Q}{k\sqrt{A_i}(T_i - T_o)}$$

Inner and Outer Boundary Shapes

### Model Development

• Thermal resistance for spherical shells

$$R = \frac{1}{2 \pi k} \left( \frac{1}{d_i} - \frac{1}{d_o} \right) \implies S_{\sqrt{A_i}}^* = \frac{2\sqrt{\pi}}{\left( 1 - \frac{d_i}{d_o} \right)}$$

• Recast  $R, S^*_{\sqrt{A_i}}$  based on gap thickness

$$\delta = \frac{d_o - d_i}{2} \implies R = \frac{\delta}{\pi k d_i (d_i + 2\delta)} \implies S_{\sqrt{A_i}}^* = \frac{\sqrt{\pi} d_i}{\delta} + 2\sqrt{\pi}$$

• General model based on concentric sphere solution

$$S_{\sqrt{A_i}}^* = \frac{\sqrt{A_i}}{\delta_e} + S_{\infty}^*$$

 $S^*_{\infty}$  = inner body conduction shape factor in full-space region

 $\delta_{e}$  = effective gap spacing

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# Effective Gap Spacing – Integral Model

- Local gap thickness  $\delta(\phi, \theta)$  can be calculated in spherical coordinates for certain geometries
- Example: cube in spherical enclosure  $z, \phi=0$   $\delta(\phi, \theta) = \frac{d_o}{2} - \rho(\phi, \theta), \quad \rho(\phi, \theta) = \frac{s_i/2}{\sin \phi \cos \theta}$  $0 \le \theta \le \frac{\pi}{4}$   $\tan^{-1} \sec \theta \le \phi \le \frac{\pi}{2}$
- Effective gap spacing from area average

$$\delta_e = \frac{24}{\pi d_o^2} \int_0^{\pi/4} \int_{\tan^{-1} \sec \theta}^{\pi/2} \delta(\phi, \theta) \frac{d_o^2}{4} \sin \phi \, d\phi \, d\theta$$

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 $x = s_i/2$ 

# Effective Gap Spacing – Two-rule Model

- Equivalent spherical enclosure preserves
  - inner body surface area,  $A_i$
  - $\ ^{\circ}$  enclosed volume, V

$$d_{i} = \sqrt{A_{i}/\pi} \quad d_{o} = \left[6(V+V_{i})/\pi\right]^{1/3} \quad V_{i} = \frac{A_{i}^{3/2}}{6\sqrt{\pi}} \quad \delta_{e} = \frac{d_{o}-d_{i}}{2}$$

• Conduction shape factor with two-rule model

$$S_{\sqrt{A_i}}^* = \frac{2\sqrt{\pi}}{\left[1 + 6\sqrt{\pi} \left(\frac{V^{1/3}}{\sqrt{A_i}}\right)^3\right]^{1/3} - 1} + S_{\infty}^*$$



### Model Validation

- Models validated for seven enclosure configurations
  - geometrically similar boundary shapes
    - cubes, cylinders, base-attached double cones
  - different boundary shapes
    - cube in spherical enclosure
    - sphere in cubical enclosure
    - cuboid in cubical enclosure
    - circular cylinder in cubical enclosure
- Validation performed using numerical data
  - existing data from literature
  - FLOTHERM<sup>7</sup> CFD simulations



# **Geometrically Similar Boundary Shapes**

Concentric cubes

$$S_{\sqrt{A_i}}^* = \frac{2\sqrt{\pi}}{\left(1 + \frac{\sqrt{\pi}}{6} \left[\left(\frac{s_o}{s_i}\right)^3 - 1\right]^{1/3}\right] - 1} + 3.391$$

• Cylinders h/d = 1

$$S_{\sqrt{A_i}}^* = \frac{2\sqrt{\pi}}{\left(1 + \frac{2}{\sqrt{6}} \left[ \left(\frac{d_o}{d_i}\right)^3 - 1 \right]^{1/3} \right] - 1} + 3.443$$

• Base-attached double cones h/d = 1

$$S_{\sqrt{A_i}}^* = \frac{2\sqrt{\pi}}{\left(1 + \sqrt{2}\left[\left(\frac{d_o}{d_i}\right)^3 - 1\right]^{1/3}\right] - 1} + 3.471$$

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#### Geometrically Similar Boundary Shapes



# **Enclosures with Different Boundary Shapes**

- Cube in spherical enclosure integral method  $\longrightarrow \delta_e = s_i \left( \frac{1}{2} \frac{d_o}{s_i} 0.6107 \right)$ 
  - two-rule method
- Sphere in cubical enclosure integral method  $\longrightarrow \delta_e = d_i \left( 0.6107 \frac{s_o}{d_i} \frac{1}{2} \right)$ 
  - two rule method
- Cuboid in cubical enclosure (a, b = 3.785 a, c = 2.175 a)
  - two-rule method
- Circular cylinder in cubical enclosure (h/d = 0.5)
  - two-rule method



#### **Cube in Spherical Enclosure**



#### Sphere in Cubical Enclosure



#### **Cuboid in Cubical Enclosure**



#### Circular Cylinder in Cubical Enclosure



# Summary and Conclusions

- General model for conduction shape factors for isothermal 3-D enclosures
- Two models for effective gap spacing
  - integral method limited to specific geometries
  - two-rule method applicable to all enclosures
- Excellent agreement (<3% RMS) with numerical data for geometrically similar boundary shapes
- Good agreement for enclosures with different boundary shapes

• 3 – 5 % RMS when  $V^{1/3} / \sqrt{A_i} > 1$ 



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